UNITRODE

27 - Line SCSI Terminator With Split Disconnect

FEATURES

- Complies with SCSI, SCSI-2, SCSI-3, SPI and FAST-20 (Ultra) Standards
- 2.5pF Channel Capacitance During Disconnect
- 100µA Supply Current in Disconnect Mode
- 4V To 7V Operation
- 110Ω Termination
- Completely Meets SCSI Hot Plugging
- –900mA Sourcing Current for Termination
- +500mA Sinking Current for Active Negation
- Logic Command Disconnects all Termination Lines
- Split Disconnect Controls Lines 1 to 9 and 10 to 27 Separately
- Trimmed Impedance to 5%
- Current Limit and Thermal Shutdown Protection

DESCRIPTION

The UCC5622 provides 27 lines of active termination for a SCSI (Small Computer Systems Interface) parallel bus. The SCSI standard recommends active termination at both ends of the cable.

The UCC5622 is ideal for high performance 5V SCSI systems. During disconnect the supply current is typically only 100µA, which makes the IC attractive for lower powered systems.

The UCC5622 features a split disconnect allowing the user to control termination lines 10 to 27 with disconnect one, DISCNCT1, and control terminiation lines 1 to 9 with disconnect two, DISCNCT2.

The UCC5622 is designed with a low channel capacitance of 2.5pF, which eliminates effects on signal integrity from disconnected terminators at interim points on the bus.

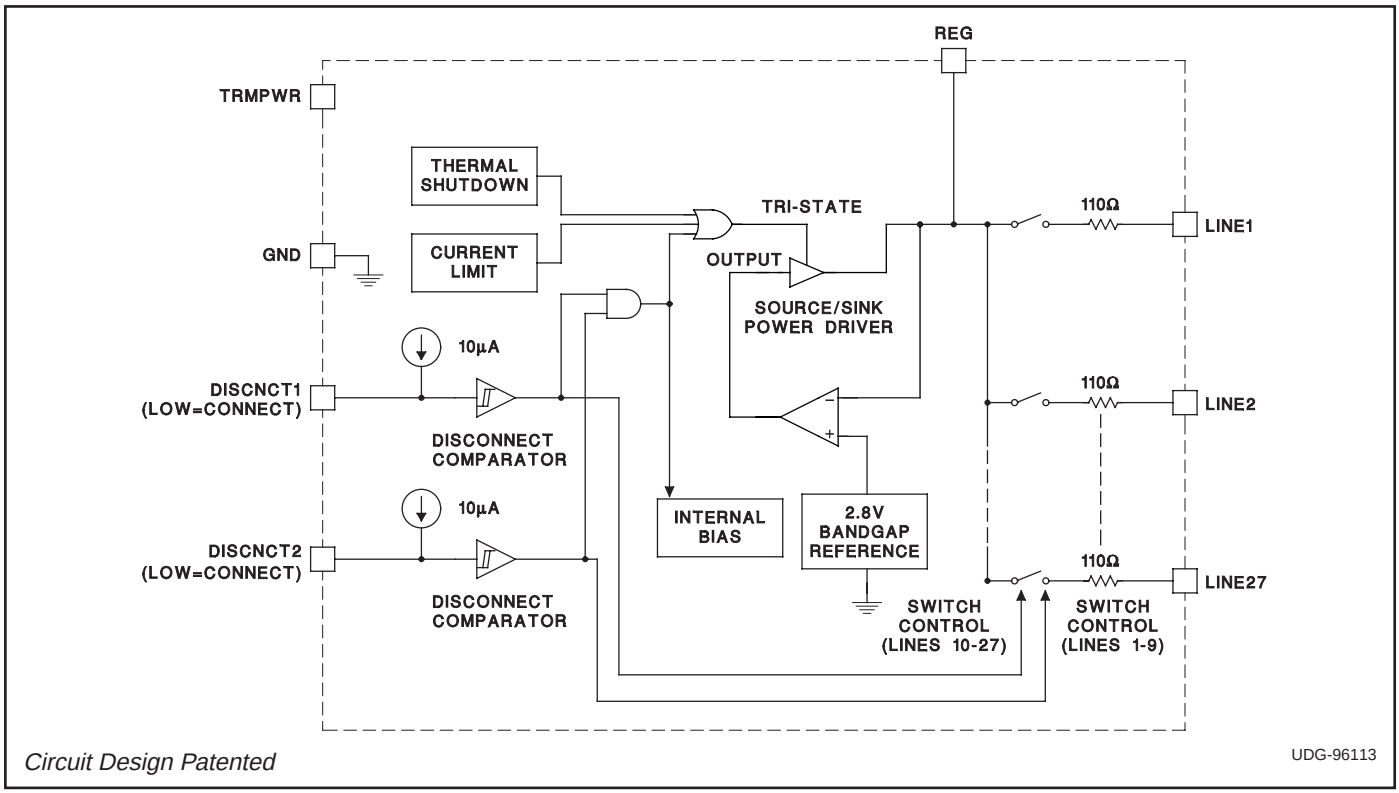
The power amplifier output stage allows the UCC5622 to source full termination current and sink active negation current when all termination lines are actively negated.

The UCC5622, as with all Unitrode terminators, is completely hot pluggable and appears as high impedance at the teminating channels with V_{TRMPWR} = 0V or open.

Internal circuit trimming is utilized, first to trim the 110Ω impedance, and then most importantly, to trim the output current as close to the maximum SCSI-3 specification as possible, which maximizes noise margin in FAST-20 SCSI operation.

(continued)

BLOCK DIAGRAM



Circuit Design Patented

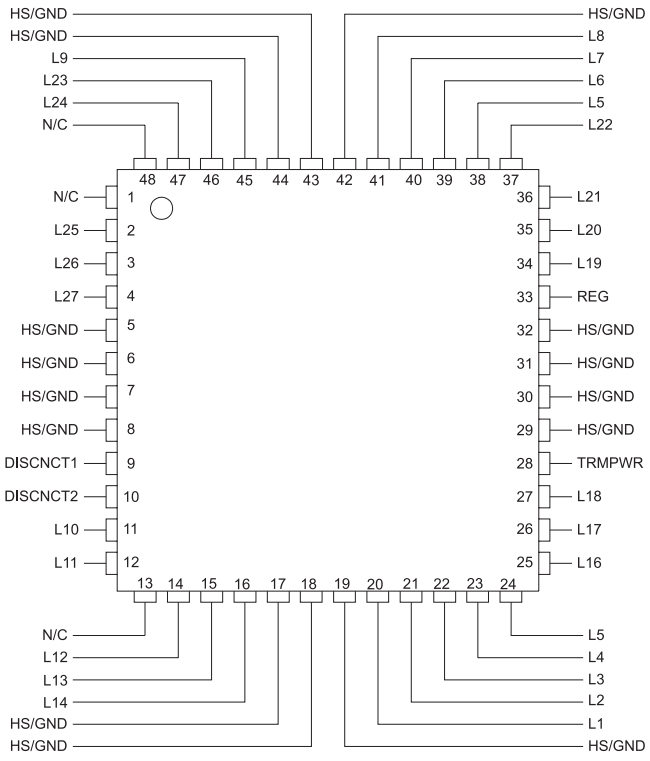
UDG-96113

ABSOLUTE MAXIMUM RATINGS

TRMPWR Voltage . . . . . +7V
Signal Line Voltage . . . . . 0V to +7V
Regulator Output Current 1.5A
Storage Temperature . . . . . –65°C to +150°C
Junction Temperature . . . . . –55°C to +150°C
Lead Temperature (Soldering, 10 Sec.). . . . . +300°C

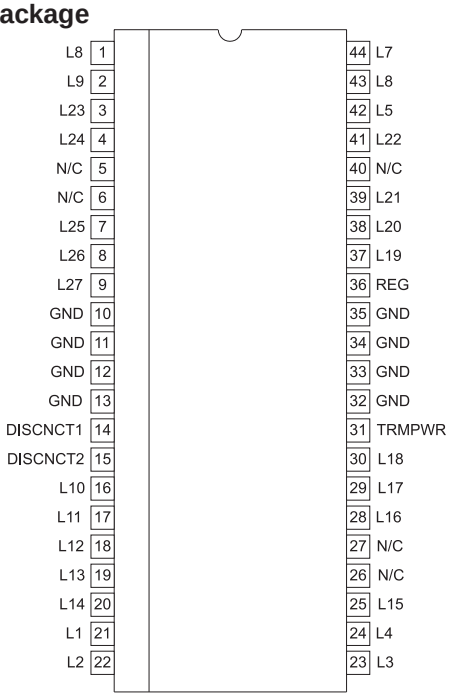
Currents are positive into, negative out of the specified terminal. Consult Packaging Section of Databook for thermal limitations and considerations of packages.

LQFP-48 (Top View)
MWP Package



CONNECTION DIAGRAM

SSOP-44 (Top View)
MWP Package



DESCRIPTION (cont.)

Other features include thermal shutdown and current limit. This device is offered in low thermal resistance versions of the industry standard 44 pin wide body QSOP (MWP) and 48 pin LQFP (FQP). Consult QSOP-44 and LQFP-48 Packaging Diagram for exact dimensions.

ELECTRICAL CHARACTERISTICS Unless otherwise stated, these specifications apply for T_A = 0°C to 70°C, TRMPWR = 4.75V, DISCNCT1 = DSCNCT2 = 0V, $T_A = T_J$.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Supply Current Section					
TRMPWR Supply Current	All Termination Lines = Open		1	2	mA
	All Termination Lines = 0.2V		630	650	mA
Power Down Mode	DISCNCT1 = DSCNCT2 = TRMPWR		100	200	µA

ELECTRICAL CHARACTERISTICS Unless otherwise stated, these specifications apply for T_A = 0°C to 70°C, TRMPWR = 4.75V, DISCNCT1 = DSCNCT2 = 0V, $T_A = T_J$.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Output Section (Termination Lines)					
Termination Impedance	(Note 3)	104.5	110	115.5	Ω
Output High Voltage	(Note 1)	2.6	2.8	3.0	V
Max Output Current	V_{LINE} = 0.2V, T_J = 25⊃C	–22.1	–23.3	–24	mA
	V_{LINE} = 0.2V	–20.7	–23.3	–24	mA
	V_{LINE} = 0.2V, TRMPWR = 4V, T_J = 25°C (Note 1)	–21	–23	–24	mA
	V_{LINE} = 0.2V, TRMPWR = 4V (Note 1)	–20	–23	–24	mA
	V_{LINE} = 0.5V			–22.4	mA
Output Leakage	DISCNCT1 = DISCNCT2 = 2.4V, TRMPWR = 0V to 5.25V		10	400	nA
Output Capacitance	DISCNCT1 = DISCNCT2 = 2.4V (Note 2)		2.5	4	pF
Regulator Section					
Regulator Output Voltage		2.6	2.8	3.0	V
Drop Out Voltage	All Termination Lines = 0.2V		0.4	0.8	V
Short Circuit Current	V_{REG} = 0V	–650	–900	–1300	mA
Sinking Current Capability	V_{REG} = 3.5V	300	500	900	mA
Thermal Shutdown			170		°C
Thermal Shutdown Hysteresis			10		°C
Disconnect Section					
Disconnect Threshold DISCNCT1	Controls Lines 10 to 27	0.8	1.5	2.0	V
Input Current DISCNCT1	DISCNCT1 = 0V		–10	–30	µA
Disconnect Threshold DISCNCT2	Controls Lines 1 to 9	0.8	1.5	2	V
Input Current DISCNCT2	DISCNCT2 = 0V		–10	–30	µA

Note 1:Measuring each termination line while other 26 are low (0.2V).
Note 2:Guaranteed by design. Not 100% tested in production.
Note 3: Tested by measuring I_{OUT} with V_{OUT} = 0.2V and V_{OUT} with no load, then calculate:

$$Z = \frac{V_{OUT}\,N.L. - 0.2V}{I_{OUT}\,at\,2.0V}$$

PIN DESCRIPTIONS

DISCNCT1: Disconnect one controls termination lines 10 – 27. Taking this pin high or leaving it open causes termination lines 10 - 27 to become high impedence, taking this pin low allows the channels to provide normal termination.

DISCNCT2: Disconnect two controls termination lines 1 – 9. Taking this pin high or leaving it open causes termination lines 1 - 9 to become high impedence. Taking this pin low allows the channels to provide normal terminiation. Taking both disconnect pins high or leaving them open will put the chip in to sleep mode where it will be in low-power mode.

GND: Ground reference for the IC.

L1 – L27: 110Ω termination channels.

REG: Output of the internal 2.7V regulator.

TRMPWR: Power for the IC.

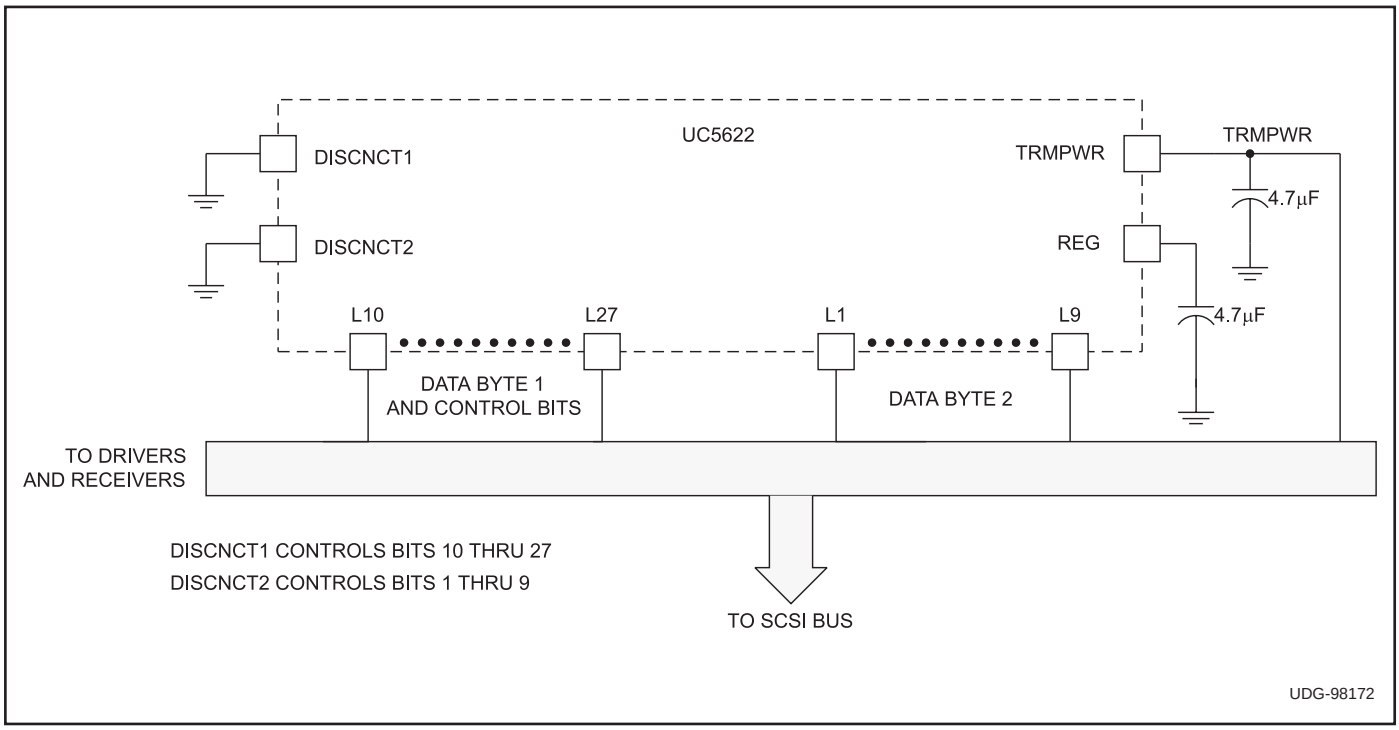


Figure 1. Typical Wide SCSI Bus Configuration Using the UCC5622

UNITRODE CORPORATION
7 CONTINENTAL BLVD • MERRIMACK, NH 03054
TEL (603) 424-2410 • FAX (603) 424-3460

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